

Sensors and Materials
Special Issue on
Materials, Devices, Circuits, and Analytical Methods for Various
Sensors
(Selected Papers from ICSEVEN 2023)

Call for Papers

The era of ubiquitous sensing has begun recently thanks to the rapid development of IoT. Sensors are essential components of automotive electronic systems used in modern applications including smart industries, smart cities, smart cars, robots, smart buildings and homes. This issue will focus on all aspects of research and development related to materials, devices, circuits, readout circuits, modules, sub-systems, systems, analytical software, deep learning, and artificial intelligence (AI) for sensor applications.

We invite authors to contribute original research as well as comprehensive review articles on the recent progress in materials, devices, circuits, analytical methods, and applications related to various sensors. Potential topics include, but are not limited to:

- Sensor materials
- Sensor devices and sensor arrays/nanosensors/MEMS sensors
- Electrochemical sensors
- Microwave sensors
- Sensor applications in industry, medicine, bio-signal monitoring, environmental monitoring, corrosion, etc.
- Analytical methods, modeling, readout circuits, and software for various sensors
- Deep learning and AI for sensor applications.
- Sensor technology and new sensor principles
- Sensor technology applications and innovative issues related to management

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If you have any questions, please feel free to contact the editorial staff at the address below.

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